NEW PRODUCT

RDBF31-RDBF310

3.0A SURFACE MOUNT FAST GLASS PASSIVATED BRIDGE RECTIFIER

Product Summary (@T_A = +25°C)

V_{RRM} (V)	I_O (A)	V_{FM} (V)	I_R (µA)
1000,800,600, 400,200,100	3.0	1.3	5

Features and Benefits

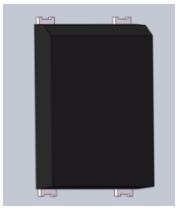
- Glass Passivated Die Construction
- Miniature Package Saves Space on PC Boards
- Low Leakage Current
- Ideal for SMT Manufacturing
- Low Forward Voltage Drop
- Fast Recovery Time for Higher Efficiency
- Surge Overload Rating to 100A Peak
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Description and Applications

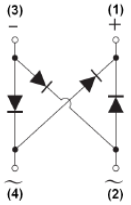
Suitable for AC to DC bridge full wave rectification for SMPS, LED lighting, adapter, battery charger, home appliances, office equipment, and telecommunication applications.

Mechanical Data

- Case: DBF
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 e3
- Polarity: As Marked on Body
- Weight: 0.02 grams (Approximate)



Top View



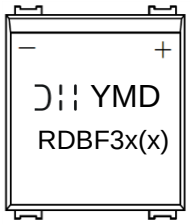
Internal Schematic

Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
RDBF310-13	Commercial	DBF	3,000/Tape & Reel
RDBF38-13	Commercial	DBF	3,000/Tape & Reel
RDBF36-13	Commercial	DBF	3,000/Tape & Reel
RDBF34-13	Commercial	DBF	3,000/Tape & Reel
RDBF32-13	Commercial	DBF	3,000/Tape & Reel
RDBF31-13	Commercial	DBF	3,000/Tape & Reel

Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



RDBF3x(x) = Product Type Marking Code
= Manufacturers' Code Marking
YMD = Date Code Marking
Y = Last Digit of Year (ex: 8 = 2018)
M = See Month/Code Table Below
D = Day 1 to 9 = 1 to 9; Day 10 to 31 = A to V

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

NEW PRODUCT

Maximum Ratings and Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	RDBF31	RDBF32	RDBF34	RDBF36	RDBF38	RDBF310	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	100	200	400	600	800	1000	V
RMS Reverse Voltage	$V_{R(RMS)}$	70	140	280	420	560	700	V
Average Rectified Output Current (Note 5) @ T_C = +120°C	I_O	3.0						A
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	100						A
I^2t Rating for Fusing (1ms < t < 8.3ms)	I^2t	41.5						A^2S
Maximum Forward Voltage (Per Element) @I_F=2.5A	V_{FM}	1.3						V
Maximum Reverse Recovery Time (Note 7)	t_{RR}	150			250	500		ns
Peak Reverse Current @T_A=+25℃ At Rated DC Blocking Voltage @T_A=+125℃	I_R	5.0 500						μA
Typical Total Capacitance (Per Element) (Note 8)	C_T	45						pF

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 6) (Per Element)	$R_{\theta JA}$	15	°C/W
Typical Thermal Resistance, Junction to Case (Per Element)	$R_{\theta JC}$	5	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Notes:
5. Device mounted on glass epoxy PC board with 1.3mm^2 solder pad.
6. Device mounted on 15mmx12mmx1.6mm Al pad attach 195mmx110mmx10mm steel plate.
7. Reverse recovery test conditions: I_F=0.5A, I_R=1.0A, I_{RR}=0.25A
8. Measured at 1.0MHz and applied reverse voltage of 4.0V D.C.

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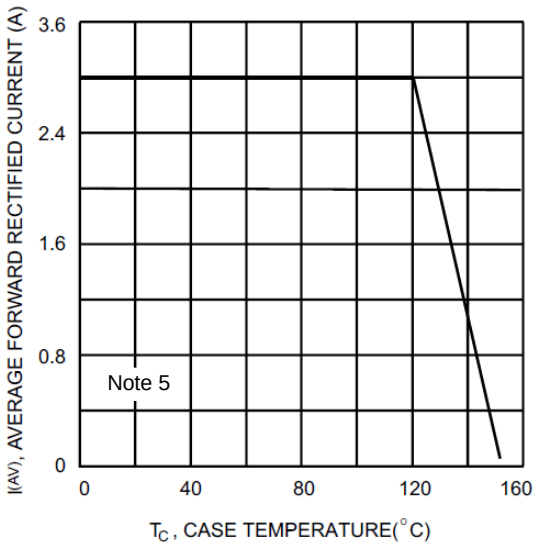

Fig. 1 Output Current Derating Curve

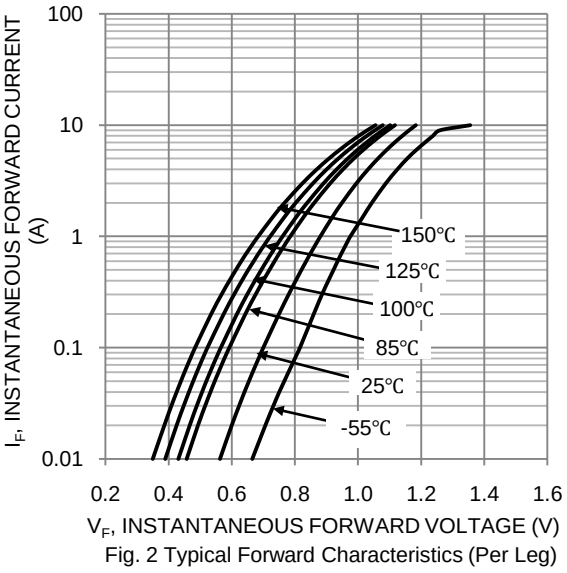

Fig. 2 Typical Forward Characteristics (Per Leg)

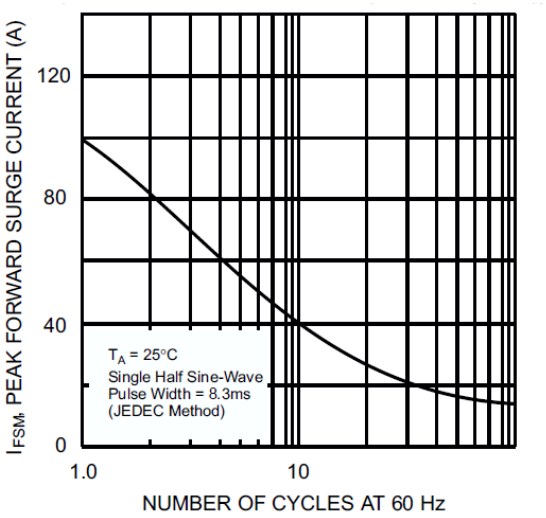

Fig.3 Maximum Non-Repetitive Surge Current

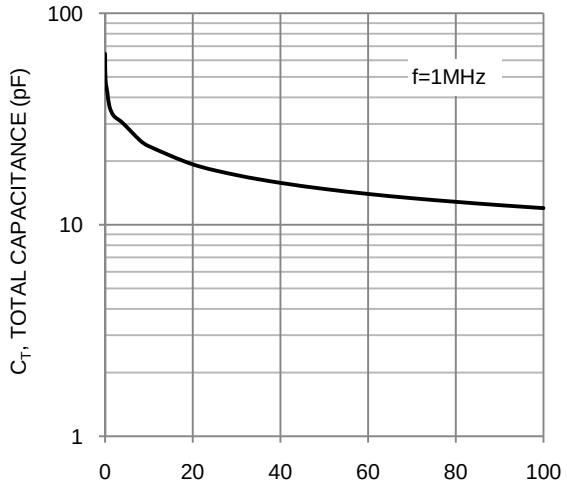

Fig. 4 Typical Total Capacitance

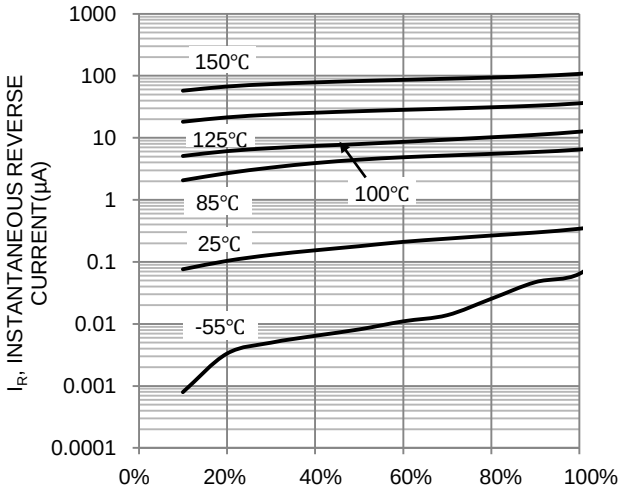

Fig.5 Typical Reverse Characteristics

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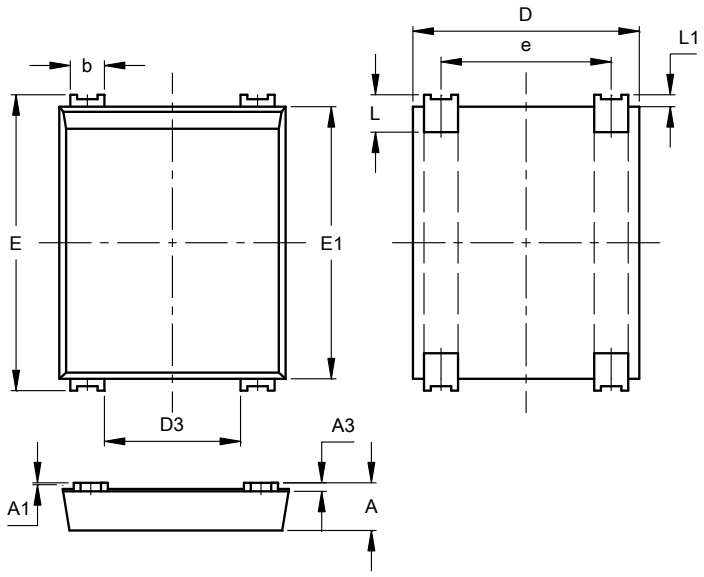
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

DBF

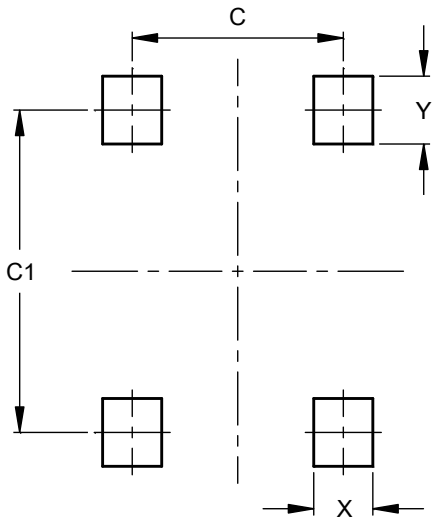


DBF			
Dim	**Min**	**Max**	**Typ**
A	1.30	1.50	--
A1	0.04	0.12	--
A3	0.15	0.35	--
b	0.80	1.20	--
D	6.45	6.85	--
D3	3.80	4.20	--
E	8.50	8.90	--
E1	7.80	8.20	--
e	4.80	5.20	--
L	0.80	1.40	--
L1	0.30	0.40	--
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

DBF



Dimensions	Value (in mm)
C	5.00
C1	7.60
X	1.40
Y	1.60

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